

Design and Implementation of BIST Architecture for low power VLSI Applications using Verilog

Mr. Aadesh Gonda
VLSI and Embedded Systems
2111706@reva.edu.in
REVA University, Bangalore

Dr. Bharathi S. H
Professor (School of ECE)
bharathish@reva.edu.in
REVA University, Bangalore

Abstract— The proposed BIST architecture focuses on minimizing power consumption during the testing phase while maintaining high fault coverage. It leverages the capabilities of the Verilog hardware description language to model and simulate the design. The research investigates various power reduction techniques, including test pattern compression, selective clock gating, and power-aware test scheduling, to optimize power consumption during testing. This research paper presents the design and implementation of a Built-In Self-Test (BIST) architecture specifically tailored for low-power Very Large-Scale Integration (VLSI) applications. The increasing demand for energy-efficient electronic devices and the proliferation of portable systems have necessitated the development of power-aware design techniques. BIST, a onchip testing technique, plays a crucial role in ensuring the quality and reliability of integrated circuits. The implementation is performed on a field-programmable gate array (FPGA) platform, demonstrating the feasibility and practicality of the proposed design. The research contributes to the field of low-power VLSI design by providing a comprehensive BIST architecture that effectively reduces power consumption during testing. The proposed design is compatible with standard Verilog synthesis and is readily applicable to a wide range of low-power VLSI applications. The findings from this study can guide designers in developing energy-efficient and reliable integrated circuits, promoting sustainability, and extending battery life in portable devices.

I. INTRODUCTION

As a result, an increasing number of transistors could be constructed onto a piece of silicon die the quick advancement in very large scale integrated (VLSI) technology. A basic example, here the state of the art 130 nanometer Complementary metal-oxide semiconductor (CMOS) manufacturing technology allows for up to eight metal layers, 80 nm poly gate lengths, and 200-300K gates/mm² silicon density. Considering the capacity to create million-gate integrated circuits (ICs), the rising chip complexity necessitates the use of sophisticated and reliable test techniques. As a result, an aspect of design that could both improve manufacturing yield and manufacturing test is emerging, which is in decline, and regulate the production cost, which is rising as a result of the growing volume of test data and testing times. Therefore, it has already been established that the most important tasks in VLSI design is to lower improve test quality while reducing test cost is essential for boosting production yield and product stability.

II. LITERATURE SURVEY

In the earlier period, several researchers and authors have investigated the implementation of BIST architecture for the detection of fault coverage and different techniques to reduce the testing power of VLSI circuits.

V.Kirthi.,et.al., [1] implemented low power BIST for a 32-bit multiplier. The seed value is changed for every two cycles by using m-bit counter and gray code is generated. The proposed technique is highly resistant to faults. Signature analysis is also done using multiple signature register. This signature indicates whether the circuit to be tested is faulty or not. Yuejian Wu.,et.al., [2] proposed a novel method has time efficiency with high grade output verification music of multiple and complex system-on-chip designs.

Katti R.S et al. [3] proposed an architecture with low power for Linear feedback Shift Register and it produces the output which gives dynamic dissipation up to 93%. The method is excellent for Built in self-Test (BIST) applications because it results in $2^N - 1$ distinct pattern for most of the degrees of N. Mohammad Tehranipoor et al. in [4] presents a low transition test pattern generator, called LT-LFSR, to reduce average and peak power of a circuit during test by reducing the transitions within random test pattern and between consecutive patterns.

Vivek A. Hadge et al., [5] designed ATPG with D-Algorithm which helps in generating a less number of input pattern for detecting faults like stuck-at-1, stuck-at-0 faults and short circuitry fault. Poornima et al. [6] presents a study Vedic multiplier architecture which has a high speed of 8x8 bit which differs greatly from the basic multiplication method like add and shift. It is a method for hierarchical multiplier design which clearly represents the computational advantages stimulated by Vedic methods.

M. Padma et al., [7] describes the BIST which concurrently monitors the input vectors called as window of vectors to create the circuit inputs during normal mode operation. CAM memory cell is used to store the relative locations of the vectors. High compression is ensured with ASDFR along with MT-filling scheme.

Bharti Mishra et.al, [8] proposed a 4-bit multiplier design used in BIST applications and the test pattern generator is designed to generate a random 4-bit number. The modified test pattern generator has a low register-to-bit ratio. The simulation and synthesis witness the efficiency of the low power implementation hardware for applications with a configurable IC.

Dong Xiang et.al [9] proposed a new method that consists of low power weighted pseudorandom pattern generator and low power data deterministic BIST with reseeding which guarantees low power operation for clock cycles and also to reduce test data kept on chip. Govindaraj Vellingiri et.al [10] designed a modified low Transition of linear feedback shift register which gives a significant randomness with equal number of 0 s and 1 s. Due to this method the switching activity by 34% and the power consumption is reduced by 36.2%.

Michal Filipek et.al [11] paper shows PRESTO the LP generator. This produces pseudo random test patterns along with scan shift-in switching and an automated programming performs this function. This method also controls the generator, so that the desired fault coverage is achieved faster. This hybrid solution allows the combination of test compression with logic BIST where the high-quality test is delivered,

In the previous works the test patterns are generated using normal polynomial that generates random test vectors and repeated test patterns. Some of the faults were not covered using this normal polynomial and it increases the switching activity in test patterns. The fault coverage is less, and it also increases the power because of switching activity. To overcome these disadvantages, in the proposed work the primitive polynomial is selected based on fault coverage and a new BIST architecture is proposed to reduce the switching activity.

Manufacturing Test of Integrated Circuits:

Specific IC manufacturing process fabrication irregularities may lead in some circuits functioning inappropriately. Before sending the packed circuits to the customer. Before sending the packed circuits to the user customers, manufacturing tests can assist find physical flaws (such as shorts or opens). Comprehensive defect screening, through fault diagnosis is needed after a damaged chip has been found in order to modify the manufacturing procedure and quicken the yield learning curve.

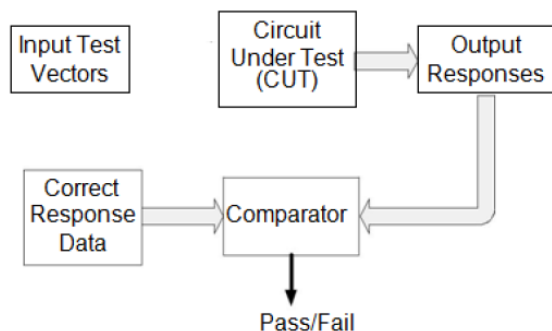


Fig. 1. Basic Principle of Digitak testing

Digital Test Methodologies: ATE vs. BIST

The fundamental idea behind production testing is depicted in Figure 1. A chip's circuit under test (CUT) may consist of the complete chip or just a portion of it (example., the logic memory block and core memory) as in Fig.1. The values observed on the CUT's outputs are the related output response to the CUT's inputs are subjected to binary patterns denoted as that of the input test vectors. External testing additionally to internal testing by using built-in self-test using automatic test equipment (ATE). The required input test data vectors and the accurate answer The ATE memory retains data when external testing is used. Using ATPG tools, input test vectors are generated, and circuit modelling is used to get accurate response data. For external testing, the tester is used for the comparison. Despite the fact that ATE-based testing was the norm In the past, whenever chip to port ratio and circuit operating frequencies expanded, here an expanding disparity circuit test and ATE capabilities standards.

System-on-a-Chip Test Challenges:

System-on-a-chip (SoC) designers are capable of combining most of the active constituents contained in a conventional system-on-a-board (SOB) into a single silicon die as manufacturing technologies keep on developing. To accomplish this, a chip must be constructed using The reasons for switching from ATE-based SOC testing to BIST are discussed here along with a number of SOC test challenges.

Embedded Memory Testing:

Since transistors and/or capacitors are used in the design of memory cells, logic gates cannot accurately represent them. Memory testing cannot be done using a structural test based on a gate level netlist. But still, as was stated in the prior section, identical memory cells and incredibly simple functional activities cause memory cores to have a relatively standard structure (just read and write), making them ideal for testing functionality. Functional testing, as contrast to random logic testing, only requires a small number of deterministic test patterns to provide the appropriate fault coverage, programs for memory cores are able to be produced using scalable along with small on-chip test suite generators. Moreover, because the written data in a fault-free memory is not affected, the predicted outputs may be readily created again on-chip and minimal overhead comparison circuitry can verify the accuracy of output responses. As a result, the memory BIST circuit is less complicated than the logic BIST.

III. THEORETICAL BACKGROUND ON MEMORY TESTING

The concept behind testing the memory is explained in this chapter. The two types of memory tests are electrical (reliant on technology) and efficient (technology-independent). Electrical memory testing involves dynamic analysis for recovery, retention, and imbalance faults, IDDQ testing of DC and AC parameters, and parametric testing of DC and AC parameters. To ensure that the device satisfies the criteria for its electrical properties, includes voltage, current, and setup and hold time requirements of chip's pins, DC and AC parametric tests are utilized. Parametric testing for embedded memory is not required since they often don't have direct I/O ports attached to chip pins in SOCs as shown in Fig.2. Dynamic testing and IDDQ require a explanation of the particular process technology. In order to confirm the logical functioning of a memory core, this study focuses on technology-independent functional memory testing. As functional memory testing permits the creation of cost-efficient quick test methods, the industry generally acknowledges it as a low-cost/high-quality choice.

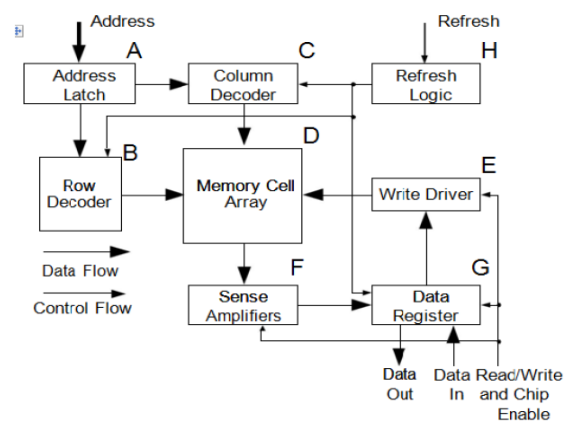


Fig. 2. Functional Memory Model

Fault Combinations:

But still, it is highly possible that many various kinds of malfunctions may exhibit simultaneously, while evaluating a memory core. These errors may or may not be interrelated. One fault present in the chain of related faults can have an impact on how other faults behave as shown in Fig.3. An unconnected defect has no effect on how other faults behave. Linked faults can also be divided into those that share the same fault type and those that share a different fault type.

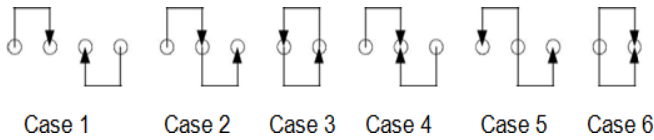


Fig. 3. Two Coupling Faults

IV. DESIGN AND IMPLEMENTATION OF BIST ARCHITECTURE USING VERILOG

BIST is the name of a method through which a machine may verify itself (or BIST It may produce patterns using a range of algorithms, each targeted towards a specific kind of circuitry or defect. There are a few different implementations of the comparison function, including signal detectors with actual comparators. We will develop Memory BIST (MBIST), which employs one or more algorithms created especially for testing memory flaws, in this project. In order to a certain part of circuitry, BIST structures, and output responses create patterns. BIST can be used to whole designs, design blocks, or structures inside of design blocks. Depending on the architecture, pattern generation and output-comparison circuitry may differ. A physical problem that arises during the production technique is referred to as a manufacturing error and results in some sort of gadget malfunction. The test patterns are produced by test generation that can identify as many manufacturing flaws as feasible.

BIST specifications: With the use of a few pins, BIST is mostly utilized to aid in the testing of memory, which has an incredibly complex architecture (fabrication-wise). Applying a straightforward clock signal and a few pins during a memory

test utilizing BIST actually aids in testing the complete memory IC.

The memory model, BIST controller, and test bench that power BIST's whole operation are designed here. Three generators—a data generator, an address generator, and a control generator—drive the finite-state machine in the BIST controller code. Additionally, MUX is utilized to choose whether to run BIST or standard memory operations.

The pattern generator, which will write and read back the same patterns in all memory locations, is used to construct and analyze BIST as shown in Fig.4.

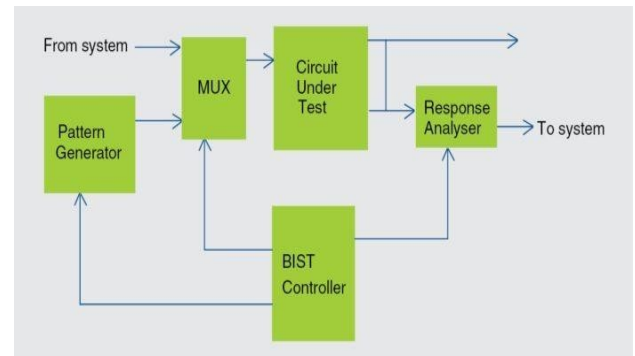


Fig. 4. Circuit with surrounding built-in self- test circuitry

We took into account 1024 inputs, each with 32-bit data. Now, a test bench will be written on Model Sim for the memory model and BIST controller in order to illustrate a stuck-type fault model in logic circuits and their pattern creation for read-and-write operations.

V. CONCLUSION

The existing limitation is that test algorithms must be March-based, even though the BIST architectures are still adaptable to heterogeneous memory. For some memory types, such huge, embedded DRAMs, Algorithms used in March-based tests are insufficient to find some physical flaws. As a result, future work can enhance the suggested designs to accommodate test procedures that are March-based and not March-based for embedded memory defects unique to DRAM. Built-in memory repair is also developing as a critical technology to boost the overall SOC yield since the yield of big, embedded memory cores is extremely low. As the designs provided in this thesis do not inherently enable self-repair, a further future improvement will be to provide explicit support for self-repair to the suggested architectures.

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